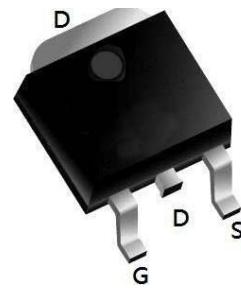
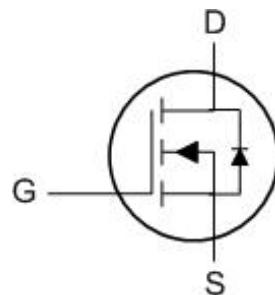


### Product Summary

BVDSS	RDSON	ID
100V	18 mΩ	50A



- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		100	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ\text{C}$	50	A
		$T_c = 100^\circ\text{C}$	30	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		150	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>		62.6	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ\text{C}$	73	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.0	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	100	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$	-	18	28	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	-	22	32	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	3727	-	pF
$C_{oss}$			-	80	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	148	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=30\text{V}$ , $I_D=15\text{A}$ , $V_{GS}=10\text{V}$	-	40	-	nC
$Q_{gs}$	Gate-Source Charge		-	6.2	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	28	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}$ , $I_D=15\text{A}$ , $R_G=1.8\Omega$ , $V_{GS}=10\text{V}$	-	22	-	ns
$t_r$	Turn-on Rise Time		-	182	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	80	-	ns
$t_f$	Turn-off Fall Time		-	142	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	50	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	150	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=30\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	IF=30A, $dI/dt=100\text{A}/\mu\text{s}$	-	71	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	145	-	nC

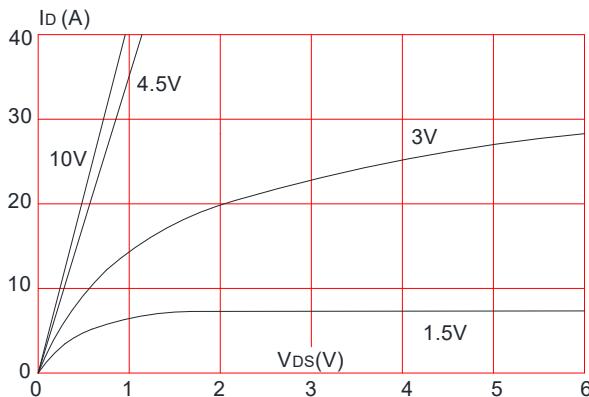
Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=50\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=14.5\text{A}$

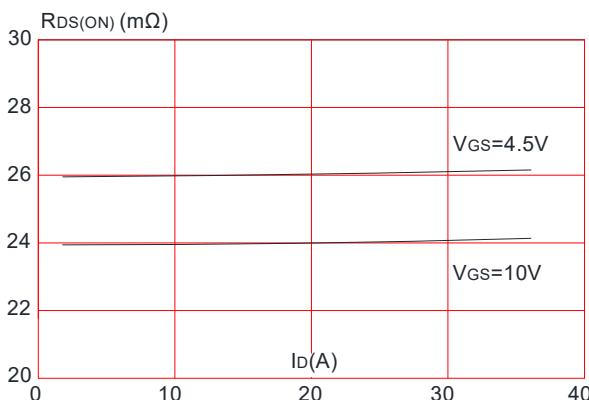
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

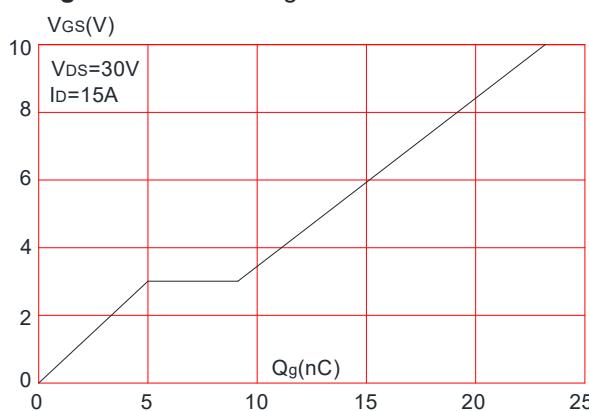
**Figure 1:** Output Characteristics



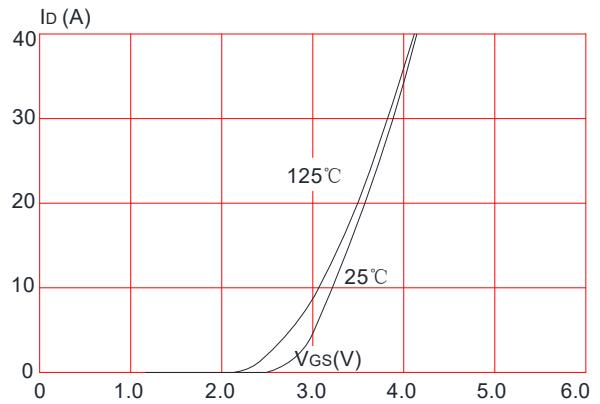
**Figure 3:** On-resistance vs. Drain Current



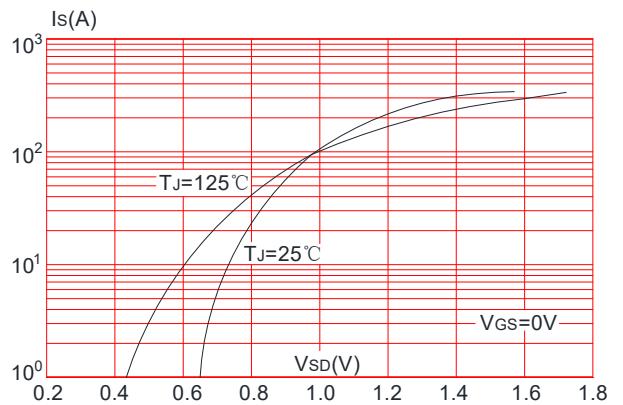
**Figure 5:** Gate Charge Characteristics



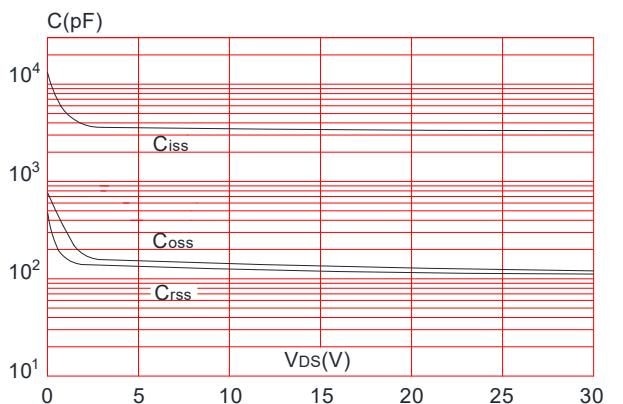
**Figure 2:** Typical Transfer Characteristics



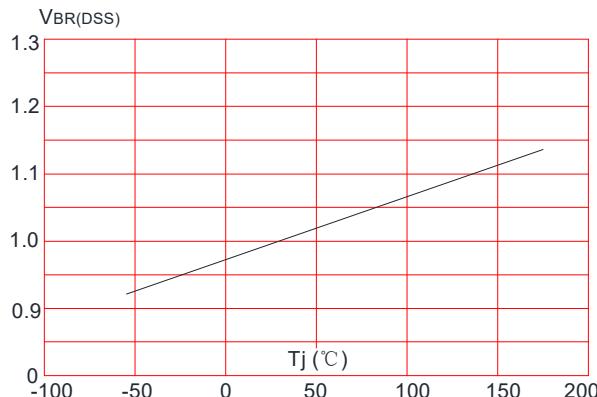
**Figure 4:** Body Diode Characteristics



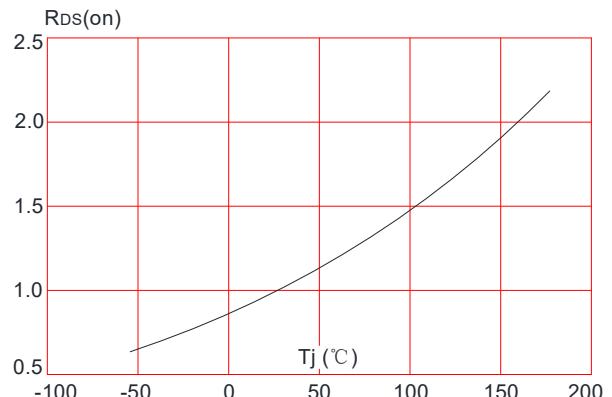
**Figure 6:** Capacitance Characteristics



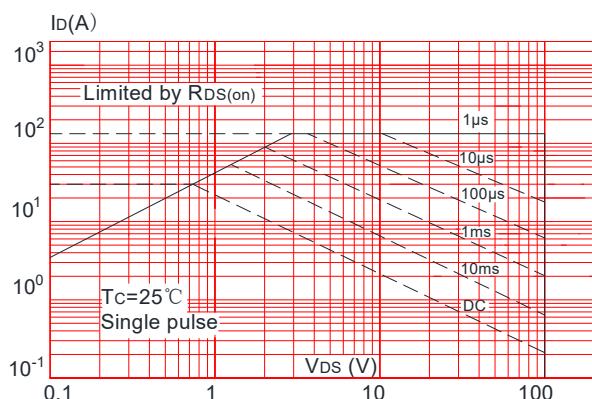
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



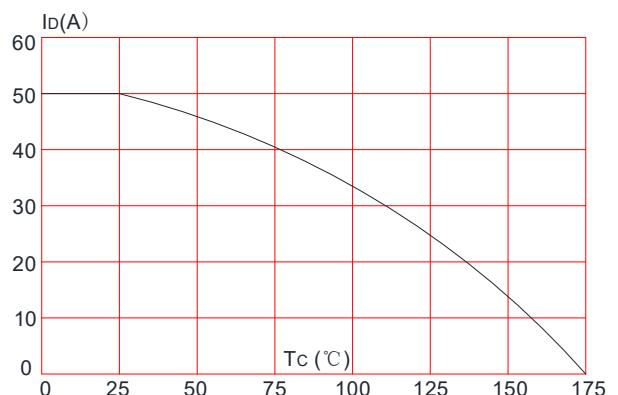
**Figure 8:** Normalized on Resistance vs. Junction Temperature



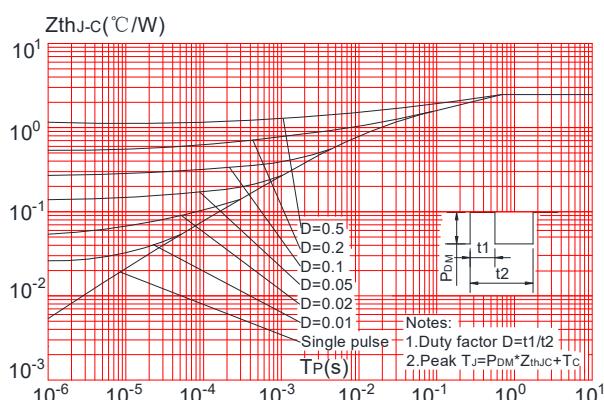
**Figure 9:** Maximum Safe Operating Area



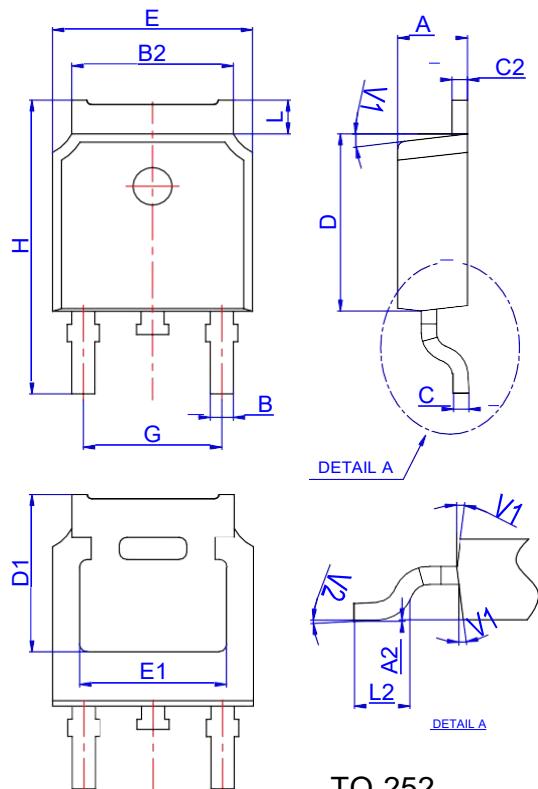
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## Package Mechanical Data TO 252



**TO-252**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

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